



AP Systems Investor Relations 2025



CREATING VALUE THROUGH TECHNOLOGIES



Contents

- I. Company Introduction
- II. The New AP Systems
- III. Financials
- IV. Business Detail



I. Company Introduction

- Company Overview
- Growth History
- Global Network and Facilities
- Major Customers

Company Overview

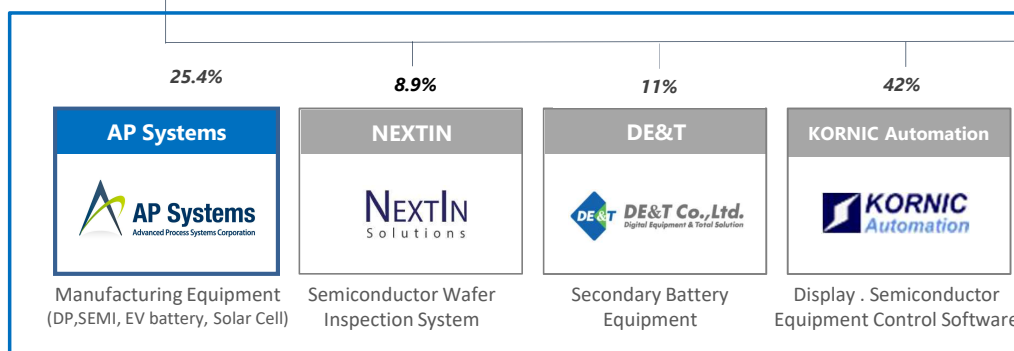


Corporate Structure



Founder : Ki Ro Jung
 - former researcher of Electronics and Telecommunication Research Institute
 - owns 32.3% shares of APS

KOSDAQ Listed Company



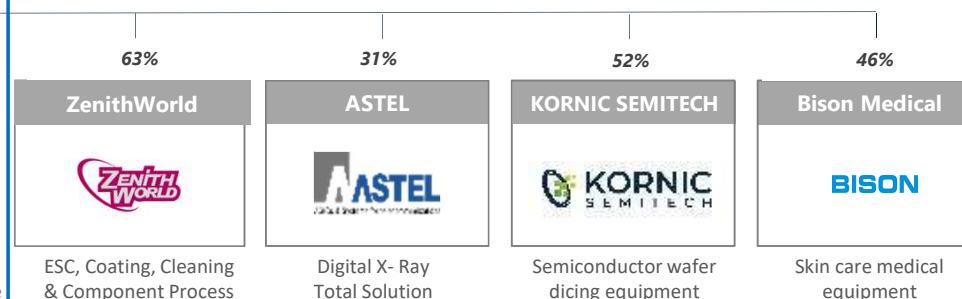
KOSDAQ Listed Company

Organization



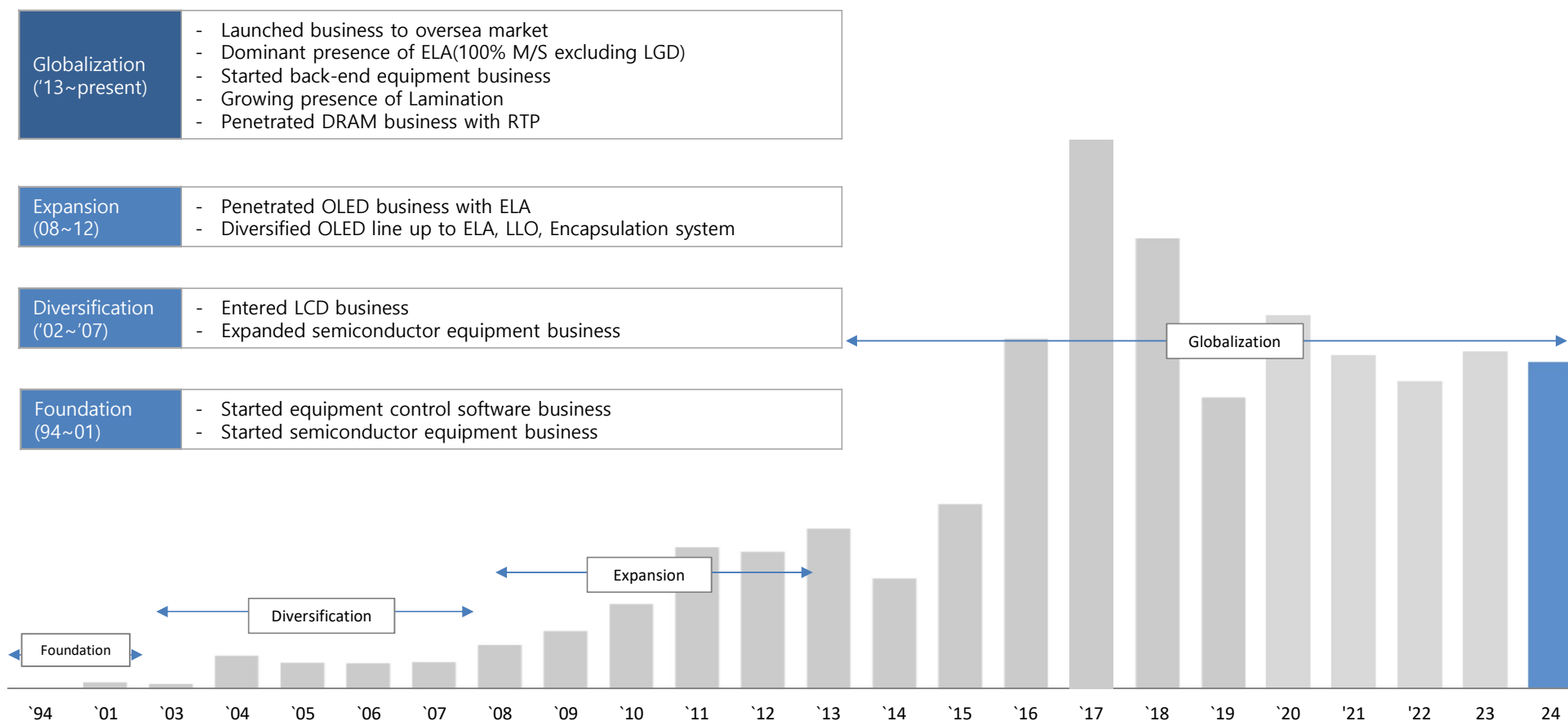
CEO : Yoo Ho Sun

- Established in 1994
 - Paid in capital : KRW 7.6 billion
 - No. of Employees : 580
- Locations: Headquarters: South Korea (Dongtan)
 Fab: South Korea (Dongtan, Balan, Cheonan)
 Overseas: China (Shanghai), Vietnam (Hanoi),
 USA (Georgia)



*AP Systems has 10.4% shares of DE&T Co.,Ltd and 9.3% of NEXTIN Inc.

Growth History



* Chart : Annual revenue

Global Network and Facilities



- Headquarters
- CS Center

APS China

Est. 2013
> Shanghai Office
> CS Centers

APS Vietnam

Est. 2016
> Hanoi Office
> CS Centers

APSYSTEMS AMERICA

Est. 2024
> Georgia Office
> CS Centers

AP Systems

Total Clean Room : 30,000m²



FAB 1 (Dongtan)

Clean Room: 5,200m²



FAB 2 (Dongtan2)

Clean Room: 4,800m²



FAB 3 (Cheonan)

Clean Room: 17,200m²



FAB 4 (Baran)

Clean Room: 2,800m²

❖ Total CAPEX capable of generating sales of \$1B

Major Customers



Semiconductor

| | | | |
|--|--|--|--|
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Display

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Renewable Energy

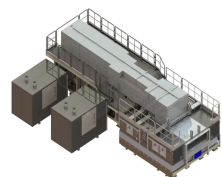
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| | |
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II. The New AP Systems

- Core Technologies
- Business & Products
- The Next Step

Core Technologies



Excimer Laser Annealing(ELA)

NEW



Laser Dicing

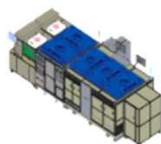
NEW



Laser Debonder



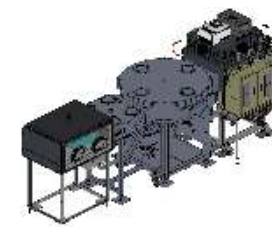
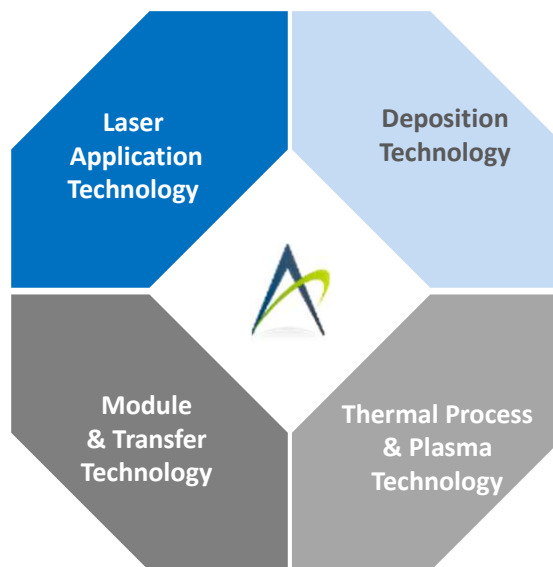
Module dispenser



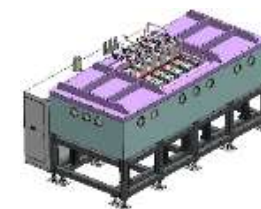
Module Laminating



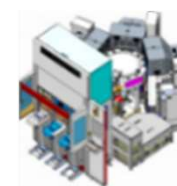
Inkjet Printer



Atomic Layer Deposition(ALD)



Sputter



Rapid Thermal Process(RTP)



Business & Products



SEMICONDUCTOR

Front-end



Rapid Thermal Process(RTP)

Back-end



Sputter



Laser Dicing



Laser De-bonder

OLED

Front-end



Excimer Laser Annealing(ELA)



Laser Lift-Off(LLO)



Encapsulation

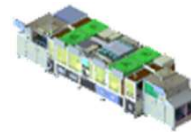


Atomic Layer Deposition(ALD)

Back-end



Module Laminating



Module dispenser



Inkjet Printer

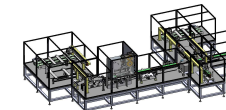
EV BATTERY



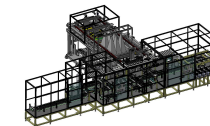
NG Sorter



Tray Washer



Cell Taping

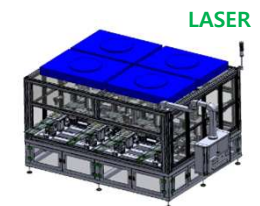


Cell Packing

SOLAR CELL

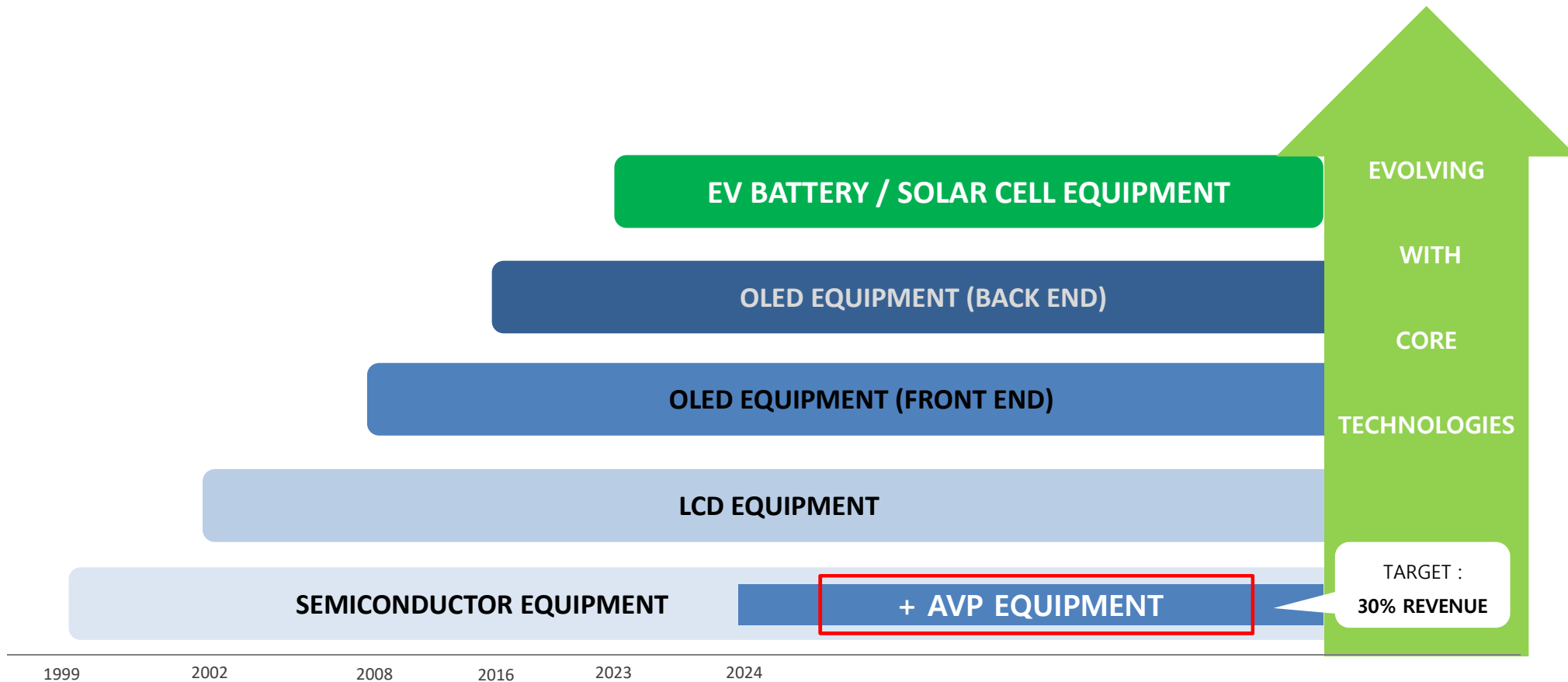


Laser Edge Isolation (LEI)



Laser Doped Selective Emitters(LDSE)

The Next Step





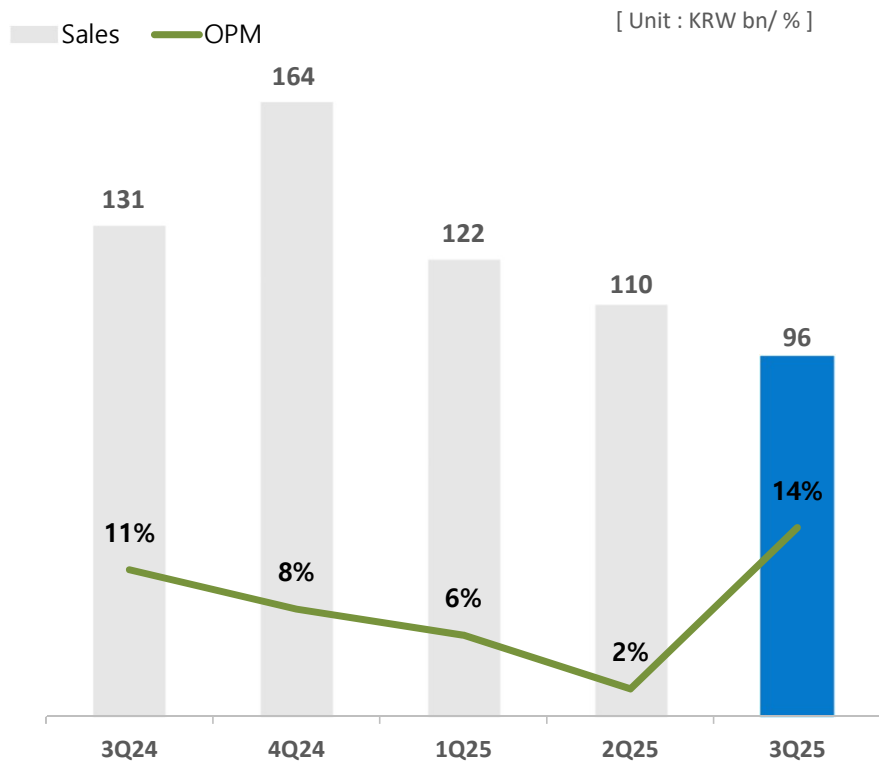
III. Financials

- Business Results : 3Q25
- Consolidated Financial Statements

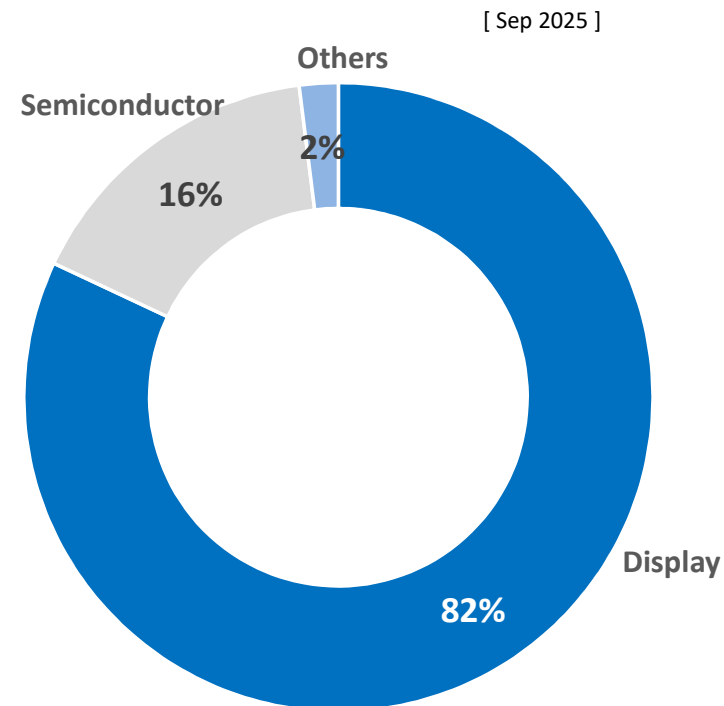
Business Results : 3Q25



Quarterly Revenue



Revenue Breakdown by Division



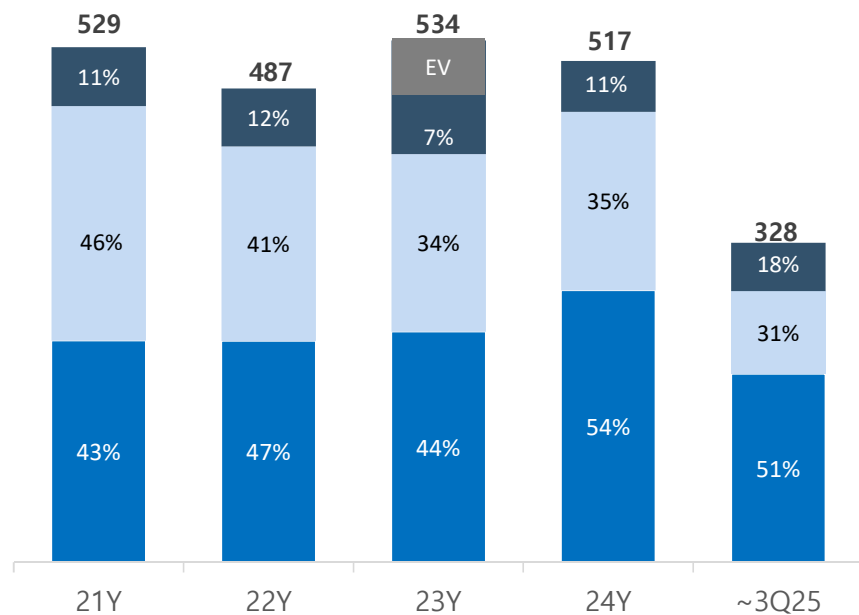
Business Results : 3Q25



Revenue Breakdown by Business Type

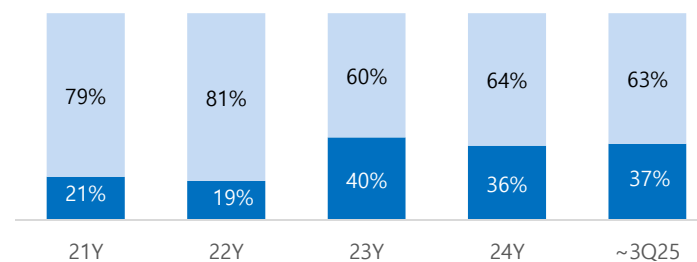
Unit : KRW bn

■ Equipment(SEMI) ■ Equipment(DP) ■ Parts



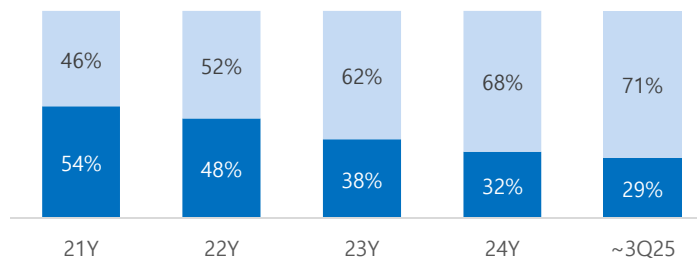
Equipment Revenue Ratio by Region

■ Domestic ■ Overseas



Parts Revenue Ratio by Region

■ Domestic ■ Overseas



Consolidated Financial Statements



Balance Sheet Summary

| [Unit : KRW bn] | 3Q25 | 2024 | 2023 | 2022 | 2021 |
|--------------------------------|------|------|------|------|------|
| Current Assets | 367 | 376 | 390 | 396 | 291 |
| Non-current Assets | 198 | 224 | 181 | 152 | 137 |
| Total Assets | 565 | 600 | 571 | 548 | 429 |
| Current Liabilities | 167 | 197 | 174 | 222 | 136 |
| Non-current Liabilities | 57 | 66 | 76 | 55 | 102 |
| Total Liabilities | 224 | 263 | 250 | 277 | 237 |
| Current Ratio (%) | 220% | 191% | 225% | 178% | 214% |
| Debt Ratio (%) | 66% | 78% | 78% | 103% | 124% |
| Total Capital | 341 | 337 | 321 | 270 | 192 |

Income Statement Summary

| [Unit : KRW bn] | ~ 3Q25 | 2024 | 2023 | 2022 | 2021 |
|---------------------------|--------|------|-------|-------|-------|
| Revenue | 328 | 517 | 534 | 487 | 529 |
| Gross Profits | 69 | 100 | 106 | 142 | 114 |
| General Expenses | 45 | 53 | 46 | 52 | 50 |
| Operating Profits | 24 | 47 | 60 | 90 | 64 |
| OP Margin(%) | 7.2% | 9.1% | 11.2% | 18.6% | 12.1% |
| Profits before Tax | 15 | 66 | 76 | 111 | 76 |
| Net Profits | 14 | 52 | 60 | 82 | 57 |

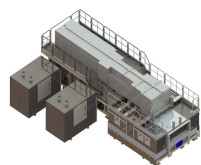
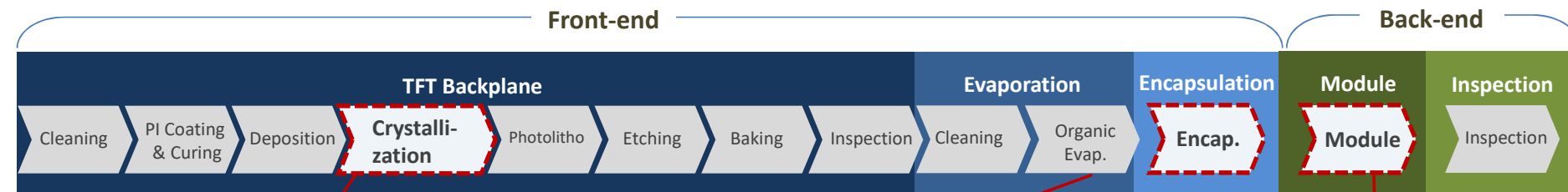
* Cumulative total



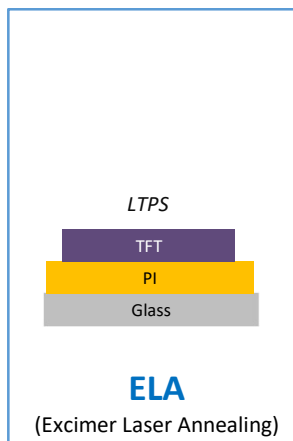
IV. Business Detail

- Display(OLED)
- Semiconductor

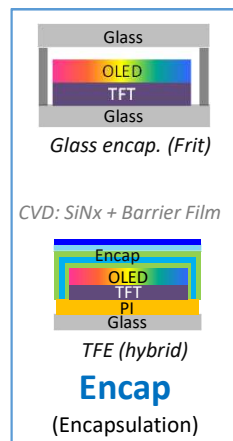
Product Line-up for Display(OLED)



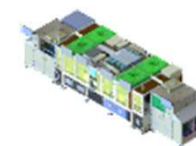
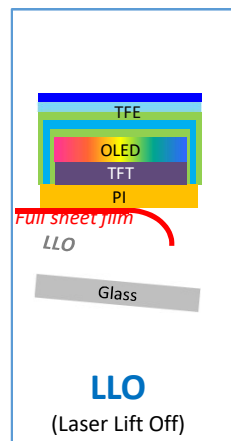
Excimer Laser Annealing



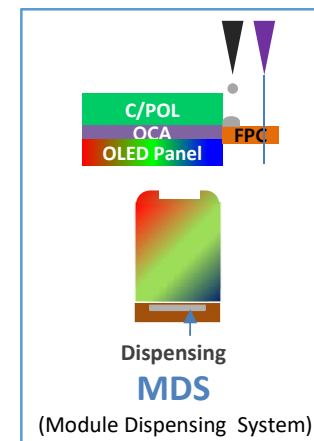
Encapsulation



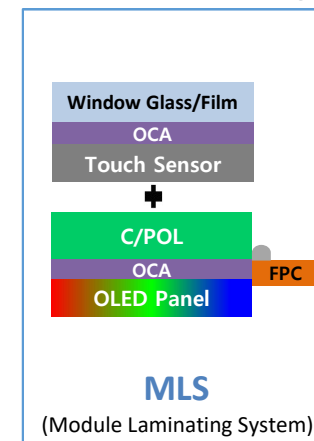
Laser Lift-Off



Module Dispensing



Module Laminating



Highlights : OLED

NOW



FRONT
END

ELA, LLO, Encapsulation

BACK
END

Laminating, Dispensing

More Demand



New Investment

&

Equipment / Parts ↑

FUTURE

Increase of OLED applications



ELA, LLO, Encapsulation + ALD

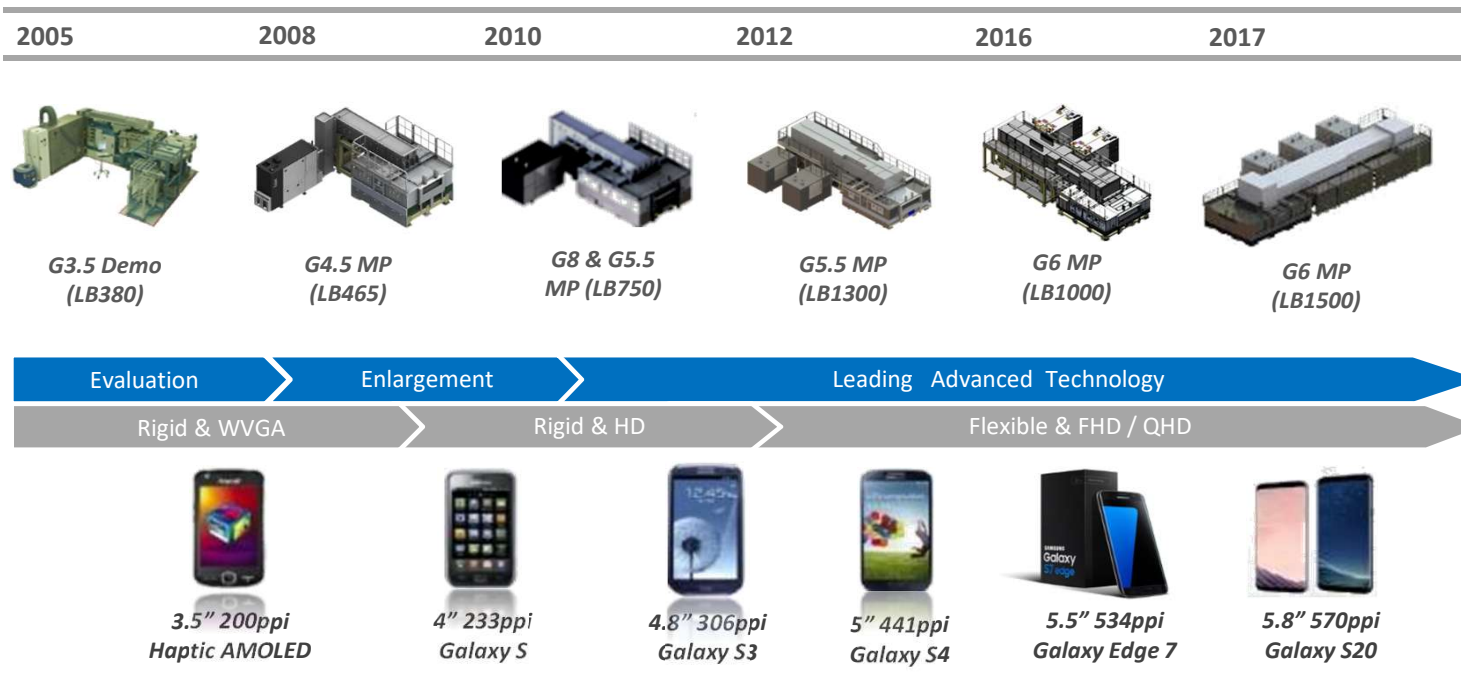
Laminating, Dispensing + OCR Inkjet Printer

Signature Equipment

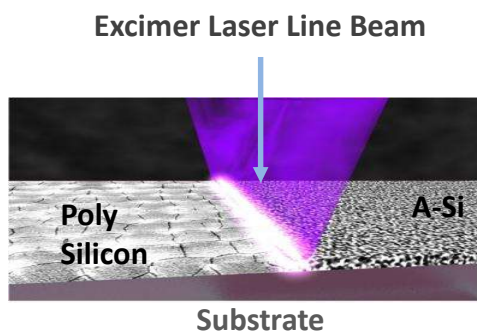
ELA (Excimer Laser Annealing)



AP Products



Customer Products

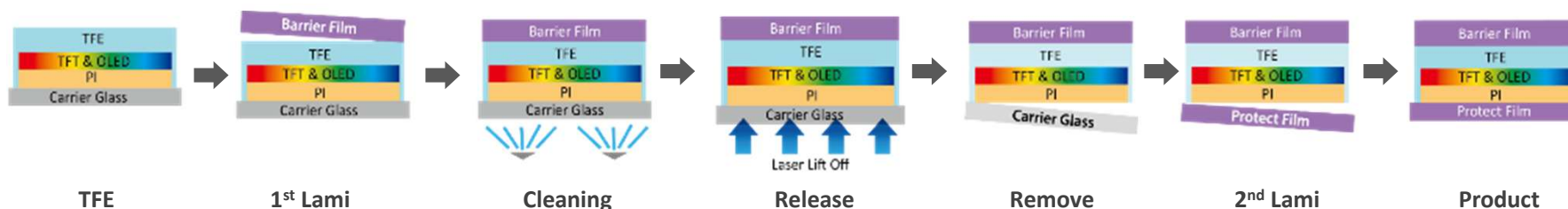


**More than 12 years experience in AMOLED*

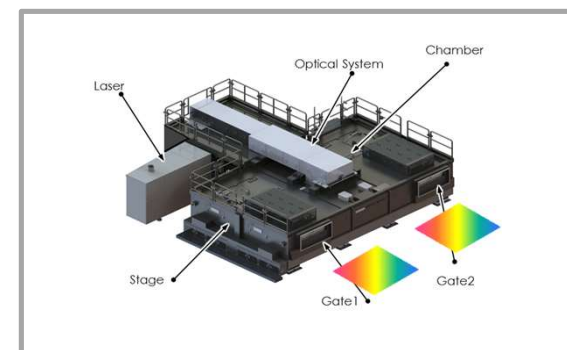
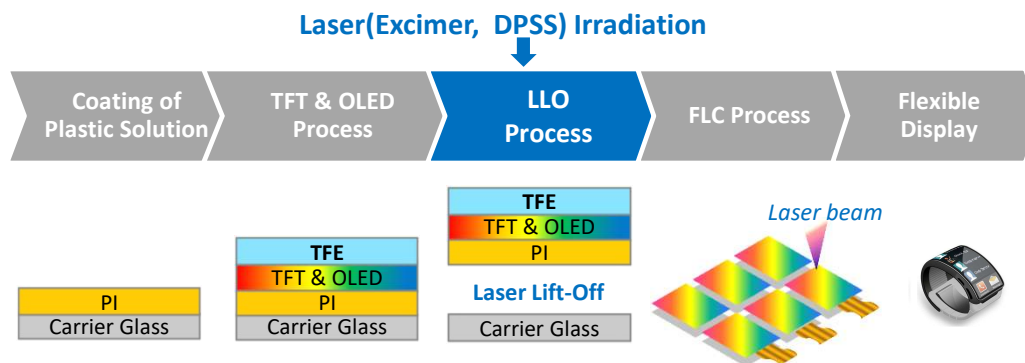
Signature Equipment

LLO (Laser Lift-Off)

Process

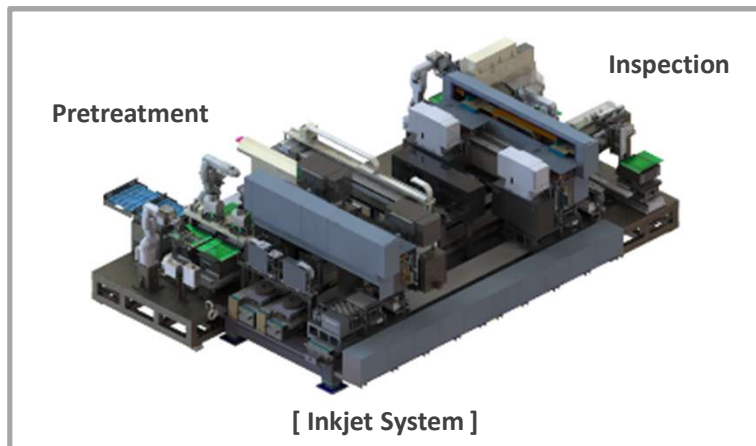


Structure



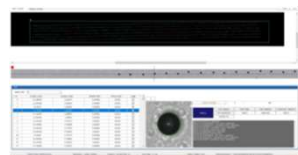
New Equipment

Module OCR IJP(Inkjet Printer)

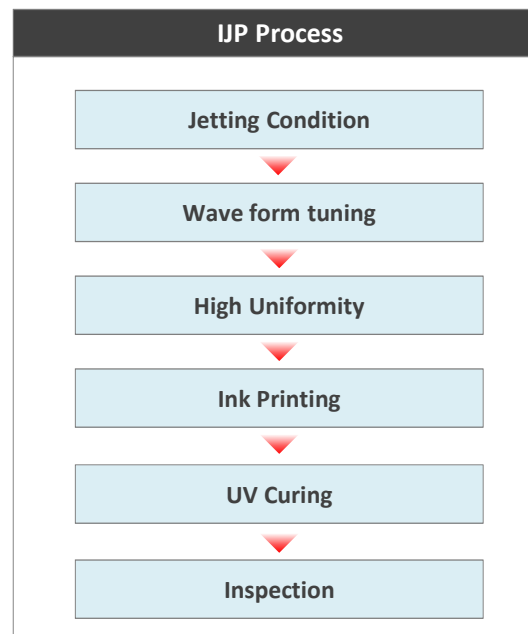


Advantage of APS' IJP

- High Performance Printing
- Easy User Interface
- Inspection : 2D , 3D , AOI
- Compact Equipment
- Best Maintenance

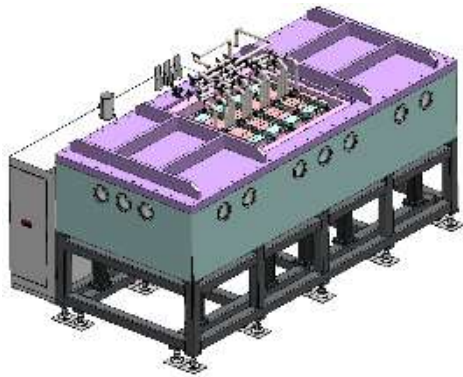


Technology



New Equipment

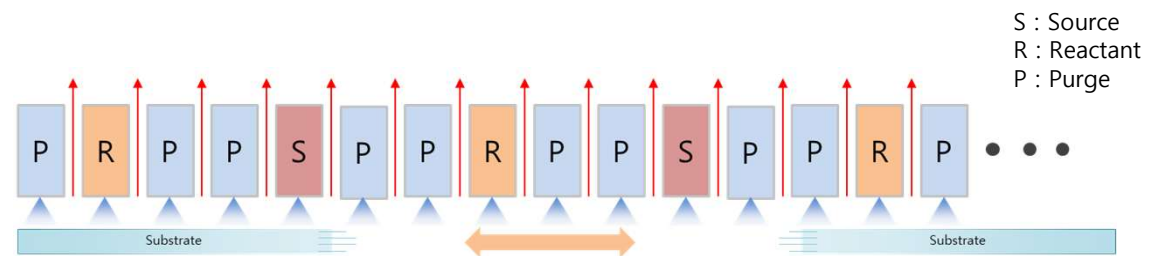
PEALD (Plasma Enhanced Atomic Layer Deposition) : M-type For 8.5G IT OLED



[M-ALD : Glass Moving]

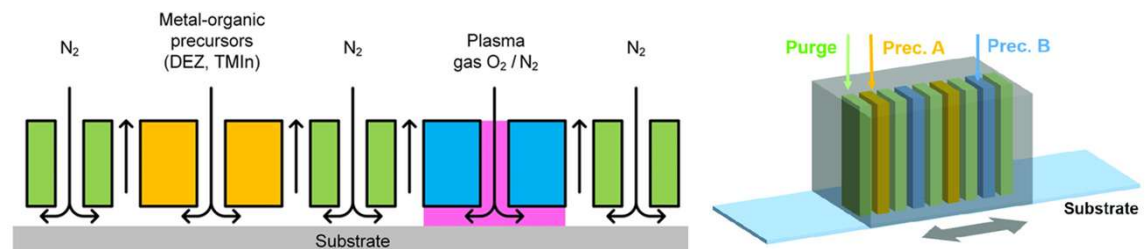
Technology

Rapid Deposition with Multiple linear nozzle & Glass moving



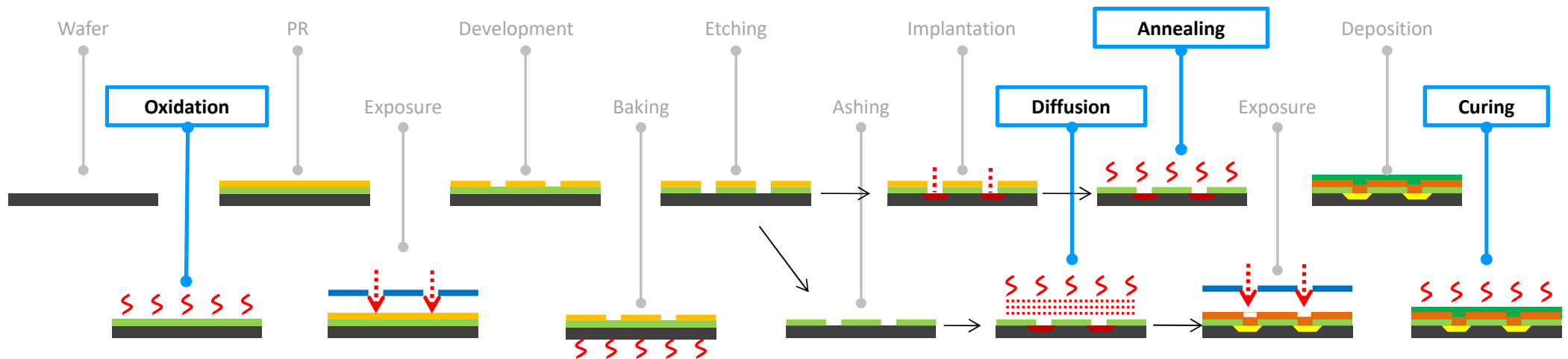
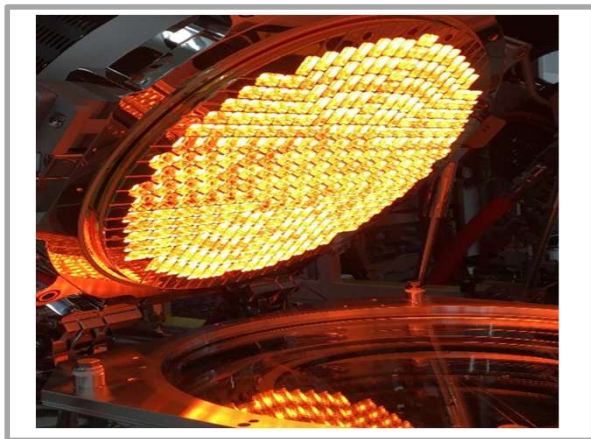
Space Divided ALD for Oxide TFT(IGZO)

- High deposition rate than Conventional ALD
→ Dep. Rate > 40Å/min
- Spatial separation of reaction, instead of time one
→ No intermixing of precursor and reactant



Signature Equipment

RTP (Rapid Thermal Process)





Thank you

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